



Technical Data Sheet

HP Polymers Ltd.
32 Kerr Cres.
Puslinch, ON, CA
N0B 2J0
519-826-0374

HP7506 - Polyamide Imide

General Information:

HP7506 polyamide imide resin provides excellent chemical and thermal resistance and is ideal for coatings which are exposed to temperatures up to 250°C.

Product Features:

- Excellent temperature resistance
- Excellent chemical resistance
- Good abrasion resistance
- FDA compliant for food contact applications when applied and fully cured

Product Specifications:

Viscosity (Brookfield)@23°C:	37 – 50 poise
Appearance:	Red/Brown Liquid
Colour:	>10
Non Volatiles (% by wt):	35 – 37% (Test 2g, 1 h @ 200°C, thinned 1:1 with NMP)
Solvent:	NMP

Typical Applications:

- Non-Stick cookware (FDA compliant)
- High Temperature coatings and binders at 240°C with excursions above 250°C
- Chemical resistant coatings for containers

Processing and Handling:

To avoid blistering during curing of the coating, the NMP solvent must be removed slowly. This is achieved by slowly removing the solvent up to the final cure temperature above 220°C. Product is hygroscopic and therefore should be stored in a manner to avoid adsorption of moisture from the atmosphere. Thinning of the resin solution and cleaning of equipment can be done using additional NMP solvent and xylene.

Storage: Product has an expected shelf life of 1 year. Exposure to humid conditions or elevated temperatures may affect physical properties of the material over time, shortening shelf life. This product is best stored at temperatures less than 25°C (77°F).

SDS: Please refer to the SDS for additional information on safe handling of this material.

NON-WARRANTY, The information presented in this publication is based upon the research and experience of HP Polymers Ltd. and is to the best of its knowledge accurate; however, no guarantee of its accuracy is made. Since HP Polymers Ltd. Has no control over the conditions under which its products may be employed; and since information as to the physiological and other properties is incomplete, HP Polymers Ltd. cannot guarantee the results obtained and assumes no liability whatsoever for possible damage or injury whether or not caused by the use of any products or processes mentioned herein. HP Polymers Ltd. will not be liable for resulting or consequential damage. This publication is not to be taken as a license to operate under, or recommendation to infringe upon any patents.